

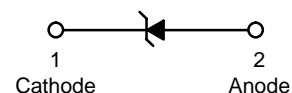
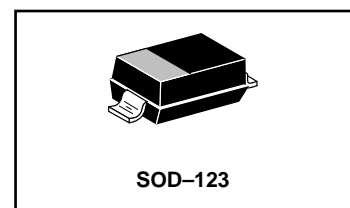
Surface Mount Schottky Power Rectifier

Plastic SOD-123 Package

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Ratings: Machine Model, C
Human Body Model, 3B
- Pb-Free Packages are Available
- We declare that the material of product compliance with RoHS requirements.

LMBR120ESFT1G



Mechanical Characteristics

- Reel Options: LMBR120ESFT1G = 3,000 per 7" reel/8 mm tape
- Device Marking: 2E
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

ORDERING INFORMATION

Device	Package	Shipping
LMBR120ESFT1G	SOD-123	3000/Tape & Reel

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	V
Average Rectified Forward Current (At Rated V_R , $T_L = 115^\circ\text{C}$)	I_O	1.0	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 100 kHz, $T_L = 110^\circ\text{C}$)	I_{FRM}	2.0	A
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	I_{FSM}	5.5	A
Storage Temperature	T_{stg}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature	T_J	-55 to 125	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R , $T_J = 25^\circ\text{C}$)	dv/dt	10,000	$\text{V}/\mu\text{s}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

LMBR120ESFT1G

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 1)	R_{tjl}	26	$^{\circ}\text{C}/\text{W}$
Thermal Resistance – Junction–to–Lead (Note 2)	R_{tjl}	21	
Thermal Resistance – Junction–to–Ambient (Note 1)	R_{tja}	325	
Thermal Resistance – Junction–to–Ambient (Note 2)	R_{tja}	82	

1. Mounted with minimum recommended pad size, PC Board FR4.
2. Mounted with 1 in. copper pad (Cu area 700 mm²).

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3), See Figure 2 ($I_F = 0.1 \text{ A}$) ($I_F = 1.0 \text{ A}$) ($I_F = 2.0 \text{ A}$)	V_F	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	V
		0.455	0.360	
		0.550	0.485	
Maximum Instantaneous Reverse Current (Note 3), See Figure 4 ($V_R = 20 \text{ V}$) ($V_R = 10 \text{ V}$) ($V_R = 5.0 \text{ V}$)	I_R	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	μA
		10	1600	
		1.0	500	
		0.5	300	

3. Pulse Test: Pulse Width $\leq 250 \mu\text{s}$, Duty Cycle $\leq 2\%$.

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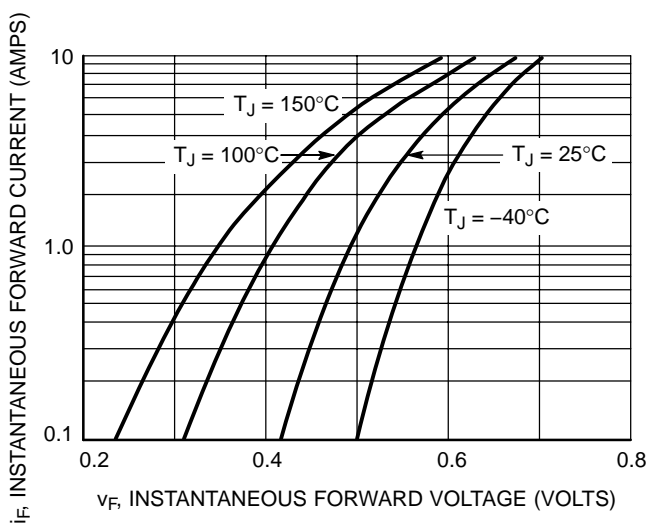


Figure 1. Typical Forward Voltage

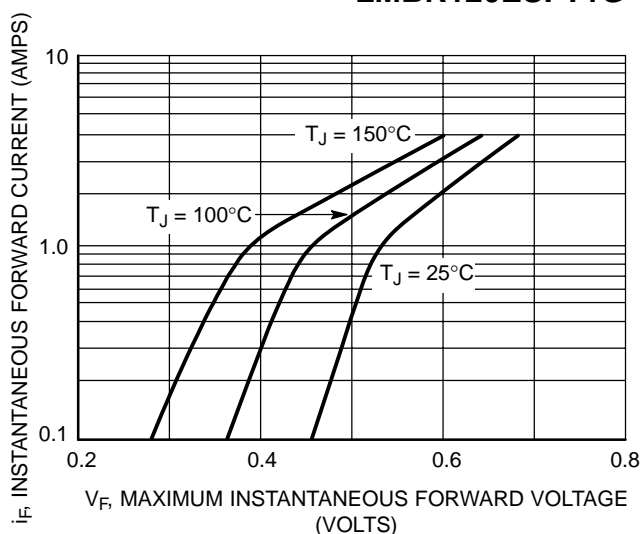


Figure 2. Maximum Forward Voltage

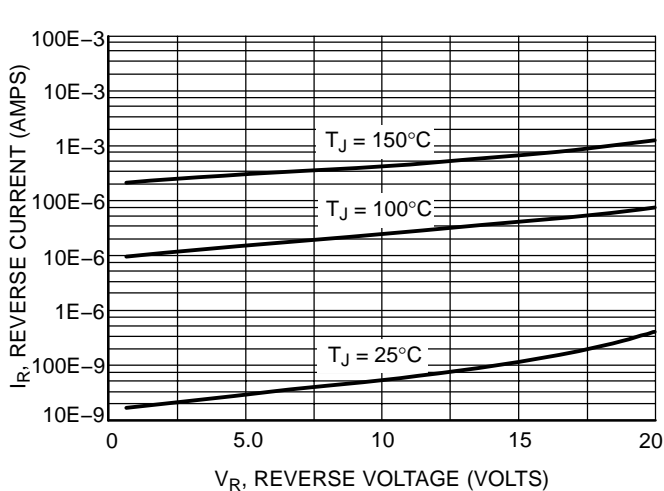


Figure 3. Typical Reverse Current

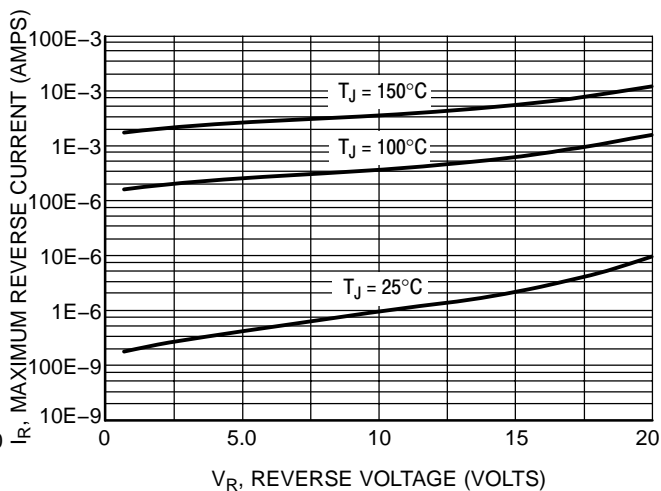


Figure 4. Maximum Reverse Current

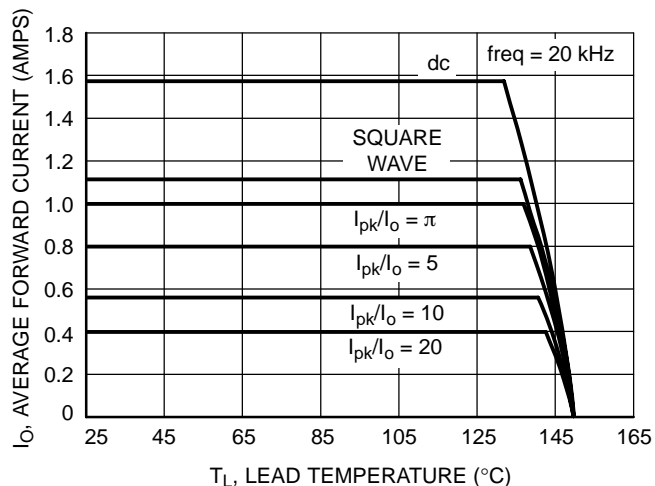


Figure 5. Current Derating

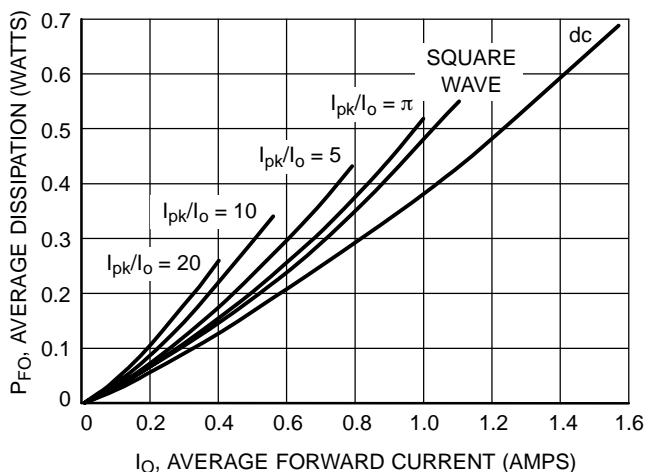


Figure 6. Forward Power Dissipation

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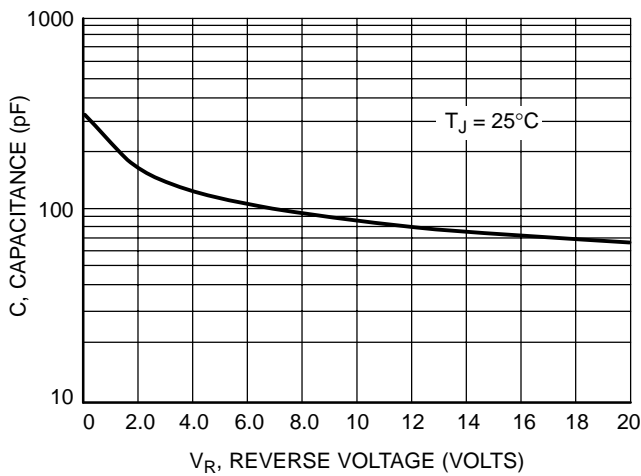


Figure 7. Capacitance

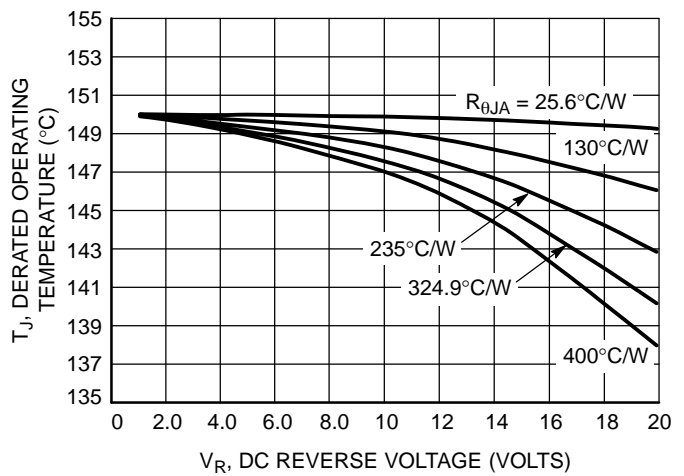


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$ = thermal impedance under given conditions,
 P_f = forward power dissipation, and
 P_r = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)P_r$, where $r(t) = R_{thja}$. For other power applications further calculations must be performed.

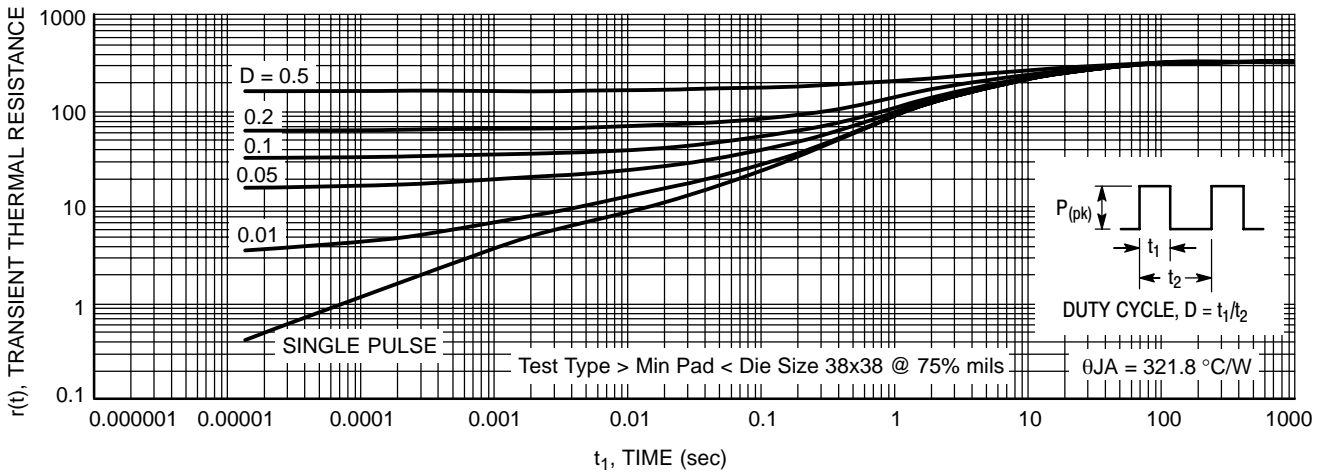
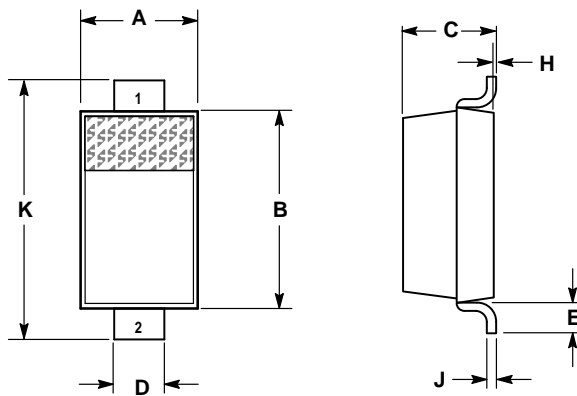


Figure 9. Thermal Response

LMBR120ESFT1G

PACKAGE DIMENSIONS

SOD-123

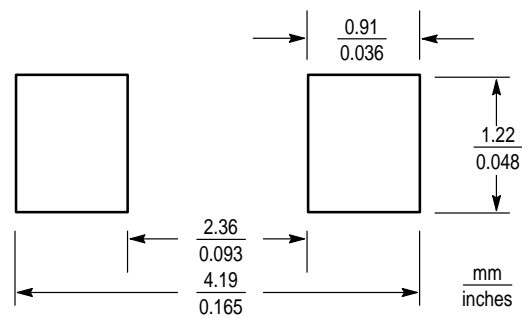


NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.055	0.071	1.40	1.80
B	0.100	0.112	2.55	2.85
C	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
E	0.004	—	0.25	—
H	0.000	0.004	0.00	0.10
J	—	0.006	—	0.15
K	0.140	0.152	3.55	3.85

STYLE 1:
 PIN 1. CATHODE
 2. ANODE

RECOMMENDED FOOTPRINT FOR SOD-123



SOD-123